



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Akram et al.

Serial No.: 09/241,177

Filed: February 1, 1999

For: HIGH DENSITY MODULARITY FOR IC'S

Examiner: Unknown

Group Art Unit: 2811

Attorney Docket No.: 3638US (98-0093)

CERTIFICATE OF MAILING

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PRELIMINARY AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

Please revise the above-identified application as follows:

IN THE SPECIFICATION:

On page 2, line 24, change "leadframe" to --lead frame--;

On page 3, line 9, insert a period at the end of this line;

On page 3, line 13, delete "areal";

On page 3, line 26, change "el al," to --et al.,--; change "are" to --is--; and change "their" to --its--;

On page 4, line 10, before "through-slots" insert --through--;

On page 4, line 11, change "are" to --is--;

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